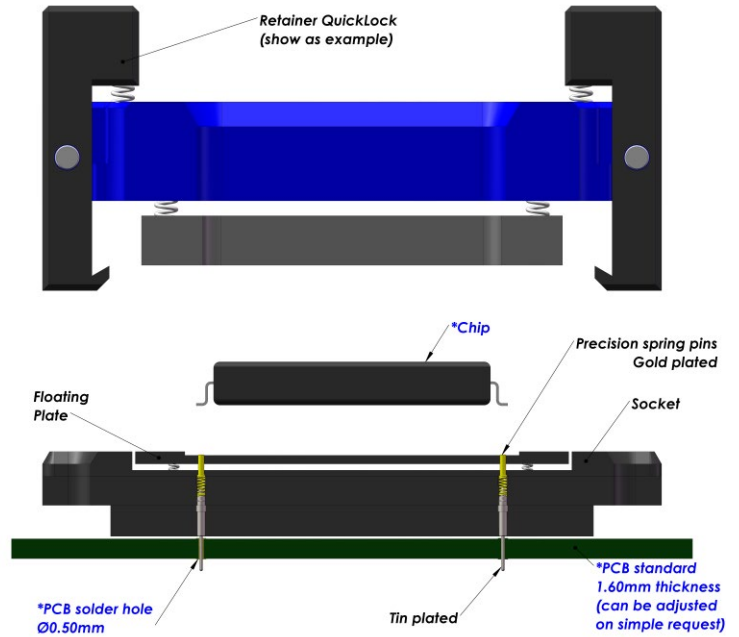
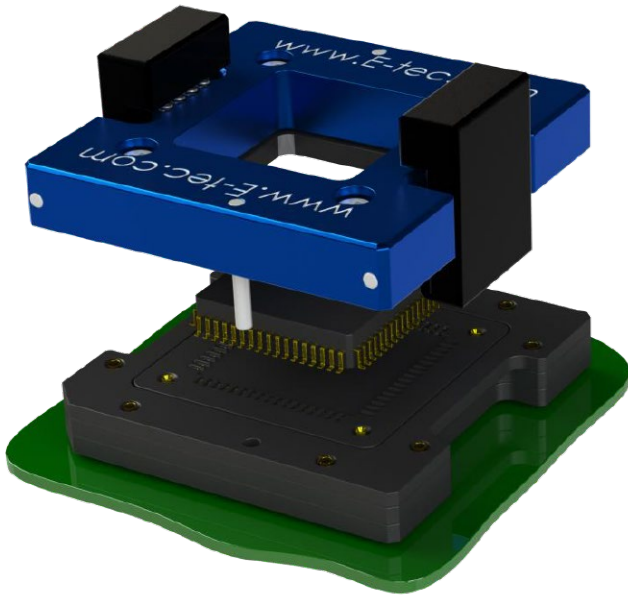
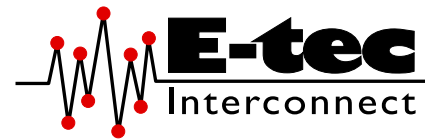


# Through-hole (THT) soldering Test Socket

For SOP / DSO / SOIC / QFP / xQFP / Flatpack Package  
**1.00 mm pitch** (from 1.00 mm up to 1.26 mm)



**E-tec Interconnect AG is the world leading Test socket manufacturer**

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 1070			
<b>Application</b>	Through-hole technology	<b>Force</b>	25 gr
<b>Mounting</b>	THT	<b>Current rating</b>	1.8 A
<b>Bandwidth (GHz@-1dB)</b>	3.4 GHz	<b>Capacitance pF</b>	1.03 pF
<b>Contact resistance</b>	<100mOhm	<b>Inductance nH</b>	1.80 nH
<b>Chip contact tip shape</b>	Single Point tip or Concave tip	<b>Temperature range</b>	-55°C to +150°C
<b>PCB tip shape</b>	Through-hole	<b>Mating cycles</b>	100 K

## How to order

**QU # #### -107# - ##### #5 #**

<p><b>Shape of tip</b></p> <p><b>U</b> : Concave</p> <p><b>Options:</b></p> <p><b>P</b> : Pointed</p>	<p><b>Nbr of contacts</b></p> <p>Depends on ballcount of chip</p>	<p><b>Contact type</b></p> <p><b>70</b> : Standard THT</p> <p><b>72</b> : Special THT to plug into MGS adapters</p>	<p><b>Plating</b></p> <p><b>95</b>: Tin / Gold</p> <p><b>55</b>: Gold / Gold</p> <p>Other on request</p>	<p><b>Option code</b> (see page 16-19)</p> <p><b>D</b> : Dead bug</p> <p><b>M</b> : Multi frames</p> <p><b>U</b> : Multi packages</p> <p><b>S</b> : Custom opening slot</p> <p><b>L</b> : Locating pegs</p> <p><b>A</b> : Alignment plate</p> <p><b>H</b> : Heatsink</p> <p><b>F</b> : Fan + Heatsink</p> <p><b>P</b> : Thermal drain pad</p> <p><b>W</b> : Transparent lid</p> <p><b>I</b> : Steel retention lid</p> <p><b>B</b> : Aluminium retention lid</p> <p><b>T</b> : Torque tool fixture</p> <p><b>G</b> : Handling button</p>
<p><b>Retention frame type (Lid)</b> (see page 12-15)</p> <p><b>S</b> : ScrewLock</p> <p><b>F</b> : FastLock</p> <p><b>B</b> : SpringLock</p> <p><b>H</b> : Open Clamshell Alu (&lt;200 contacts)</p> <p><b>J</b> : Clamshell Alu (&gt;200 contacts)</p> <p><b>L</b> : Open Lever Clamshell Alu (&gt;200 contacts)</p>		<p><b>Q</b> : Open QuickLock (&lt;200 contacts)</p> <p><b>D</b> : QuickLock (&gt;200 contacts)</p> <p><b>M</b> : Injection Molded ClamShell</p>		<p><b>Grid code / Config. code</b></p> <p>Will be given by the factory after receipt of the chip datasheet</p>

